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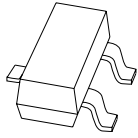
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Kind regards,

Team Nexperia



# PBRP113ZT

PNP 800 mA, 40 V BISS RET; R1 = 1 k $\Omega$ , R2 = 10 k $\Omega$

Rev. 01 — 16 January 2008

Product data sheet

## 1. Product profile

### 1.1 General description

800 mA PNP low  $V_{CEsat}$  Breakthrough In Small Signal (BISS) Resistor-Equipped Transistor (RET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

NPN complement: PBRN113ZT.

### 1.2 Features

- 800 mA repetitive peak output current
- High current gain  $h_{FE}$
- Built-in bias resistors
- Simplifies circuit design
- Low collector-emitter saturation voltage  $V_{CEsat}$
- Reduces component count
- Reduces pick and place costs
- $\pm 10\%$  resistor ratio tolerance

### 1.3 Applications

- Digital application in automotive and industrial segments
- Medium current peripheral driver
- Switching loads

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base	-	-	-40	V
$I_O$	output current		[1][2]	-	-600	mA
$I_{ORM}$	repetitive peak output current	$t_p \leq 1$ ms; $\delta \leq 0.33$	[3]	-	-800	mA
R1	bias resistor 1 (input)		0.7	1	1.3	k $\Omega$
R2/R1	bias resistor ratio		9	10	11	

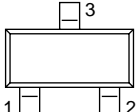
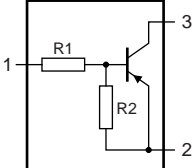
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.

[2] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	input (base)		 sym003
2	GND (emitter)		
3	output (collector)		

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBRP113ZT	-	plastic surface-mounted package; 3 leads	SOT23

## 4. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
PBRP113ZT	*7M

- [1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

## 5. Limiting values

Table 5. Limiting values

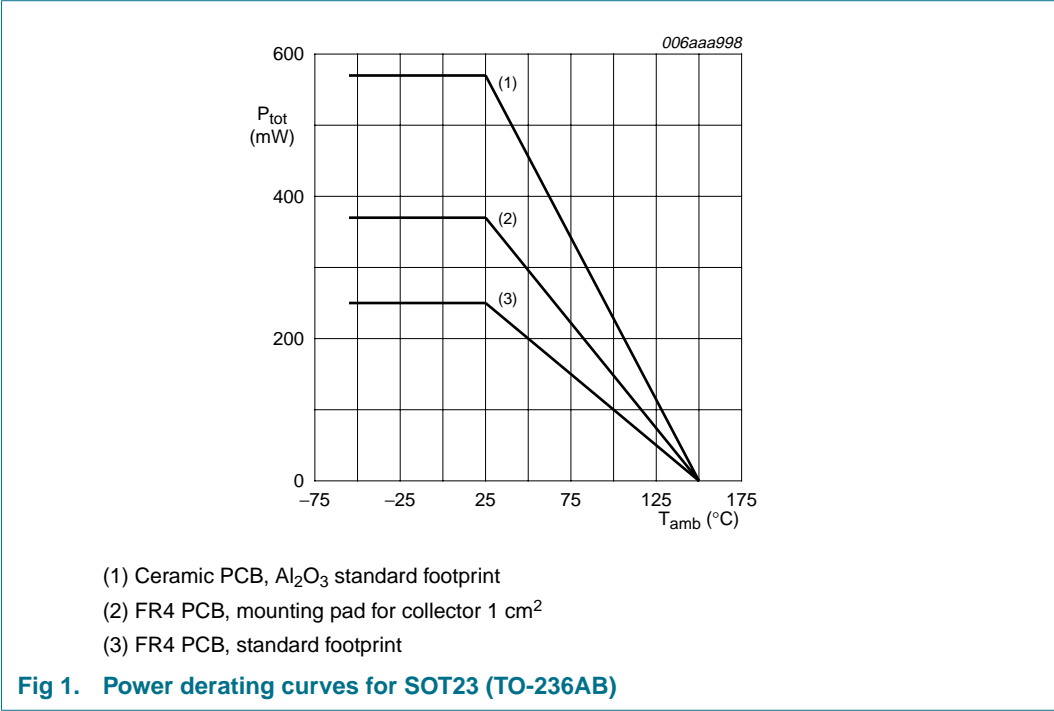
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-40	V
$V_{CEO}$	collector-emitter voltage	open base	-	-40	V
$V_{EBO}$	emitter-base voltage	open collector	-	-5	V
$V_I$	input voltage				
	positive		-	+5	V
	negative		-	-10	V
$I_O$	output current		<sup>[1][2]</sup> -	-600	mA
$I_{ORM}$	repetitive peak output current	$t_p \leq 1$ ms; $\delta \leq 0.33$	<sup>[3]</sup> -	-800	mA

Table 5. Limiting values ...continued  
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C				
			[3]	-	250	mW
			[1]	-	370	mW
			[2]	-	570	mW
T <sub>j</sub>	junction temperature		-	150	°C	
T <sub>amb</sub>	ambient temperature		−55	+150	°C	
T <sub>stg</sub>	storage temperature		−65	+150	°C	

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.  
[2] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.  
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

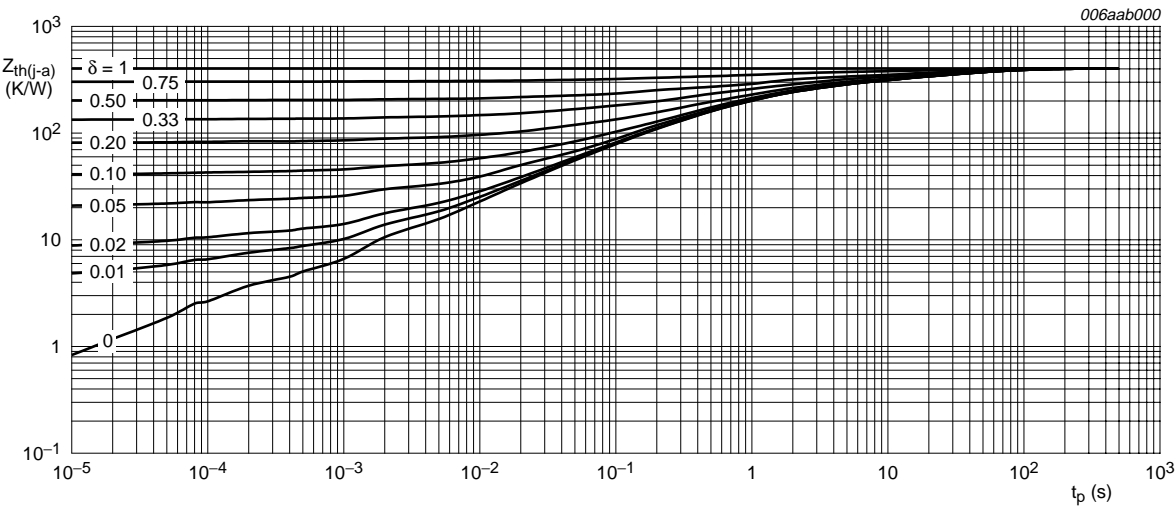


6. Thermal characteristics

Table 6. Thermal characteristics

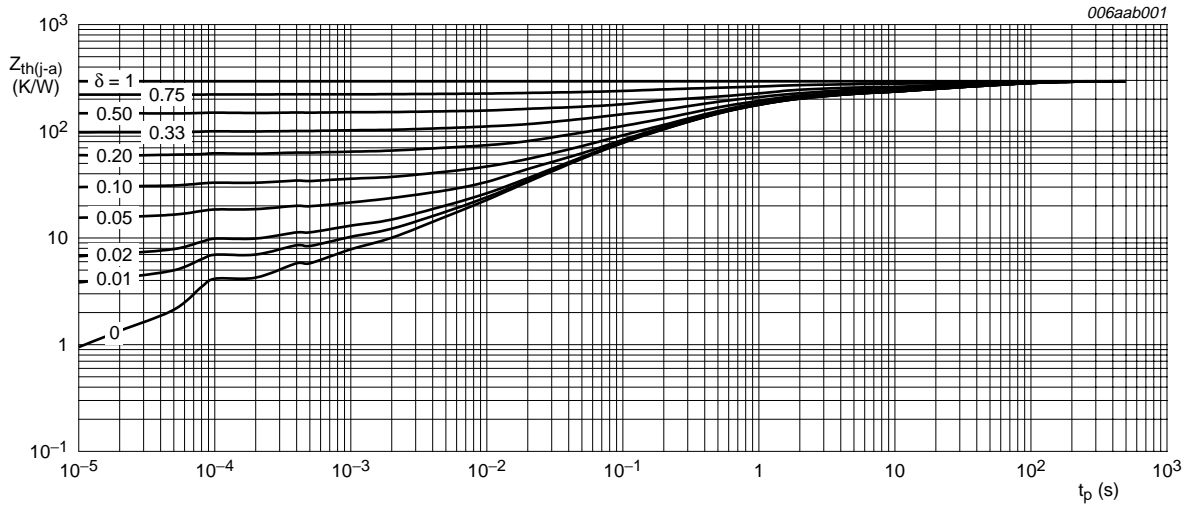
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
			[1]	-	-	500 K/W
			[2]	-	-	338 K/W
			[3]	-	-	219 K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	105	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.  
[3] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.



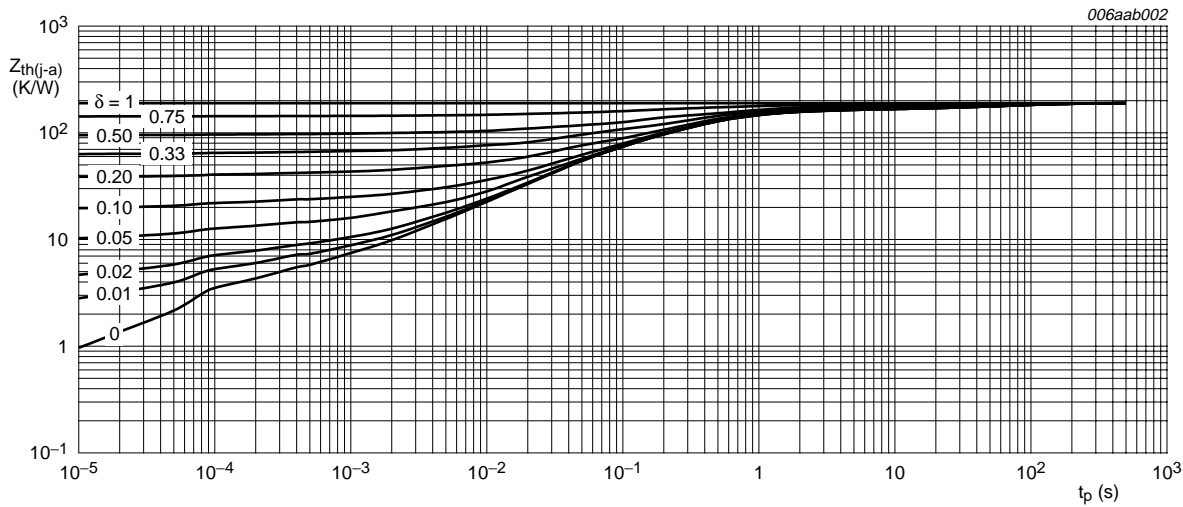
FR4 PCB, standard footprint

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT23 (TO-236AB); typical values



FR4 PCB, mounting pad for collector 1 cm<sup>2</sup>

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT23 (TO-236AB); typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub> standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT23 (TO-236AB); typical values

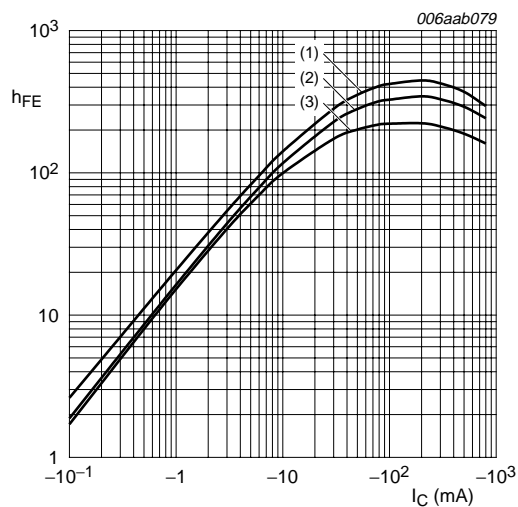
## 7. Characteristics

**Table 7. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

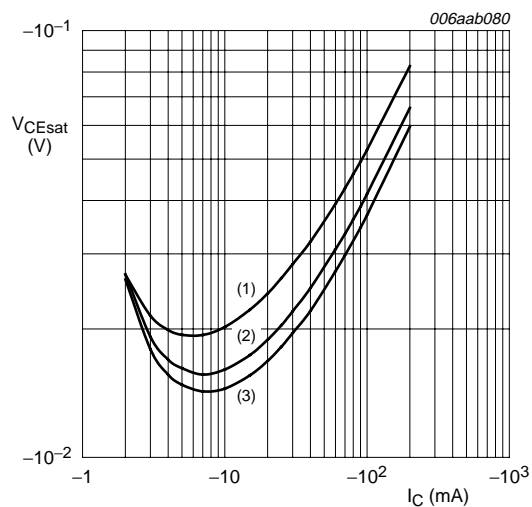
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -30\text{ V};$ $I_E = 0\text{ A}$	-	-	-100	nA
$I_{CEO}$	collector-emitter cut-off current	$V_{CE} = -30\text{ V};$ $I_B = 0\text{ A}$	-	-	-0.5	μA
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V};$ $I_C = 0\text{ A}$	-	-	-0.8	mA
$h_{FE}$	DC current gain	$V_{CE} = -5\text{ V};$ $I_C = -50\text{ mA}$	190	270	-	
		$V_{CE} = -5\text{ V};$ $I_C = -300\text{ mA}$	[1] 230	320	-	
		$V_{CE} = -5\text{ V};$ $I_C = -600\text{ mA}$	[1] 190	270	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -50\text{ mA};$ $I_B = -2.5\text{ mA}$	-	-35	-45	mV
		$I_C = -200\text{ mA};$ $I_B = -10\text{ mA}$	-	-70	-100	mV
		$I_C = -500\text{ mA};$ $I_B = -10\text{ mA}$	[1] -	-200	-300	mV
		$I_C = -600\text{ mA};$ $I_B = -6\text{ mA}$	[1] -	-450	-750	mV
$V_{I(off)}$	off-state input voltage	$V_{CE} = -5\text{ V};$ $I_C = -100\text{ μA}$	-0.3	-0.5	-1	V
$V_{I(on)}$	on-state input voltage	$V_{CE} = -0.3\text{ V};$ $I_C = -20\text{ mA}$	-0.4	-0.7	-1.4	V
R1	bias resistor 1 (input)		0.7	1	1.3	kΩ
R2/R1	bias resistor ratio		9	10	11	
$C_c$	collector capacitance	$V_{CB} = -10\text{ V};$ $I_E = i_e = 0\text{ A};$ $f = 1\text{ MHz}$	-	11	-	pF

[1] Pulse test:  $t_p \leq 300\text{ μs}$ ;  $\delta \leq 0.02$ .



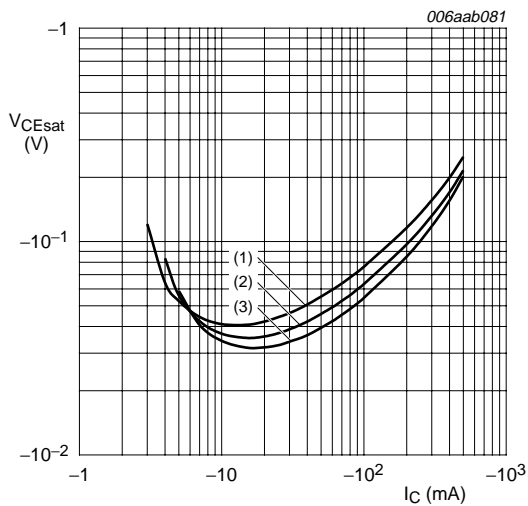
- $V_{CE} = -5\text{ V}$   
(1)  $T_{amb} = 100\text{ °C}$   
(2)  $T_{amb} = 25\text{ °C}$   
(3)  $T_{amb} = -40\text{ °C}$

Fig 5. DC current gain as a function of collector current; typical values



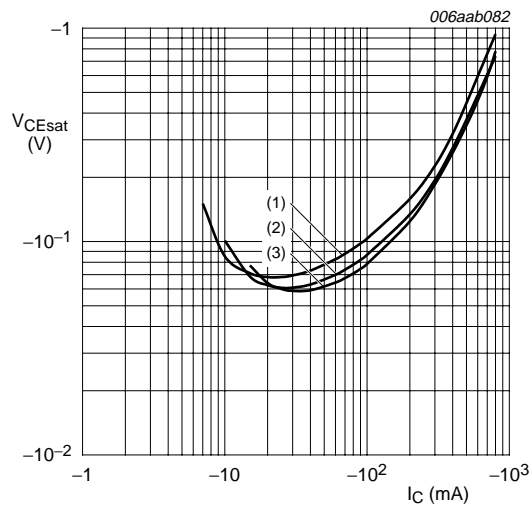
- $I_C/I_B = 20$   
(1)  $T_{amb} = 100\text{ °C}$   
(2)  $T_{amb} = 25\text{ °C}$   
(3)  $T_{amb} = -40\text{ °C}$

Fig 6. Collector-emitter saturation voltage as a function of collector current; typical values



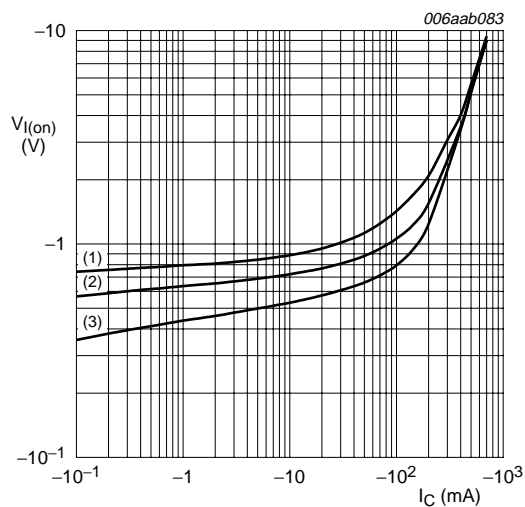
- $I_C/I_B = 50$   
(1)  $T_{amb} = 100\text{ °C}$   
(2)  $T_{amb} = 25\text{ °C}$   
(3)  $T_{amb} = -40\text{ °C}$

Fig 7. Collector-emitter saturation voltage as a function of collector current; typical values



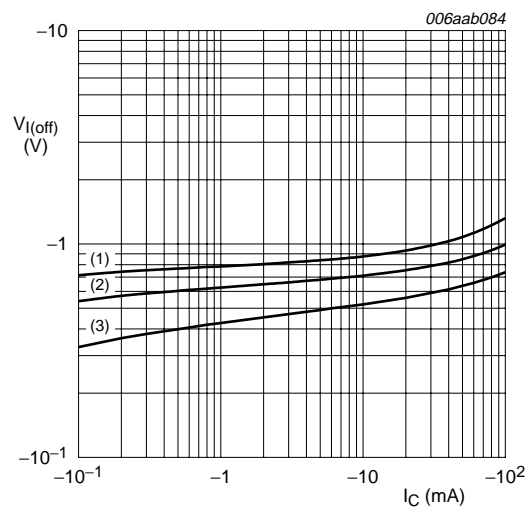
- $I_C/I_B = 100$   
(1)  $T_{amb} = 100\text{ °C}$   
(2)  $T_{amb} = 25\text{ °C}$   
(3)  $T_{amb} = -40\text{ °C}$

Fig 8. Collector-emitter saturation voltage as a function of collector current; typical values



$V_{CE} = -0.3$  V  
(1)  $T_{amb} = -40$  °C  
(2)  $T_{amb} = 25$  °C  
(3)  $T_{amb} = 100$  °C

Fig 9. On-state input voltage as a function of collector current; typical values



$V_{CE} = -5$  V  
(1)  $T_{amb} = -40$  °C  
(2)  $T_{amb} = 25$  °C  
(3)  $T_{amb} = 100$  °C

Fig 10. Off-state input voltage as a function of collector current; typical values

8. Package outline

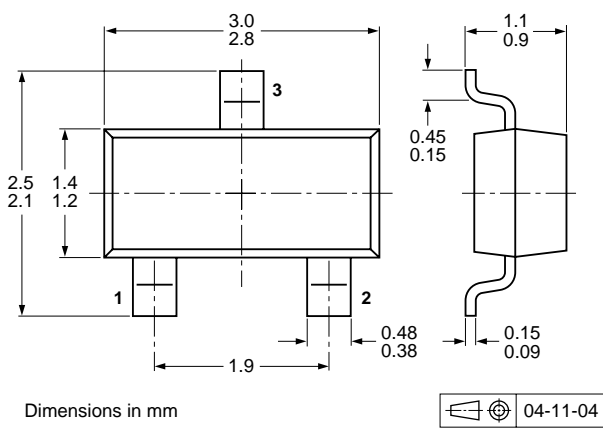


Fig 11. Package outline SOT23 (TO-236AB)

9. Packing information

Table 8. Packing methods  
The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
PBRP113ZT	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235

[1] For further information and the availability of packing methods, see [Section 13](#).

10. Soldering

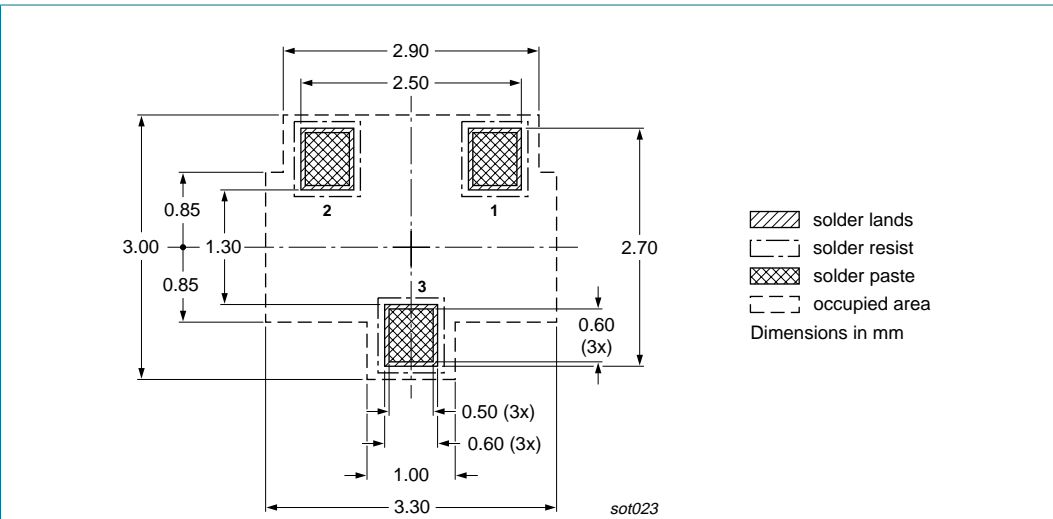


Fig 12. Reflow soldering footprint SOT23 (TO-236AB)

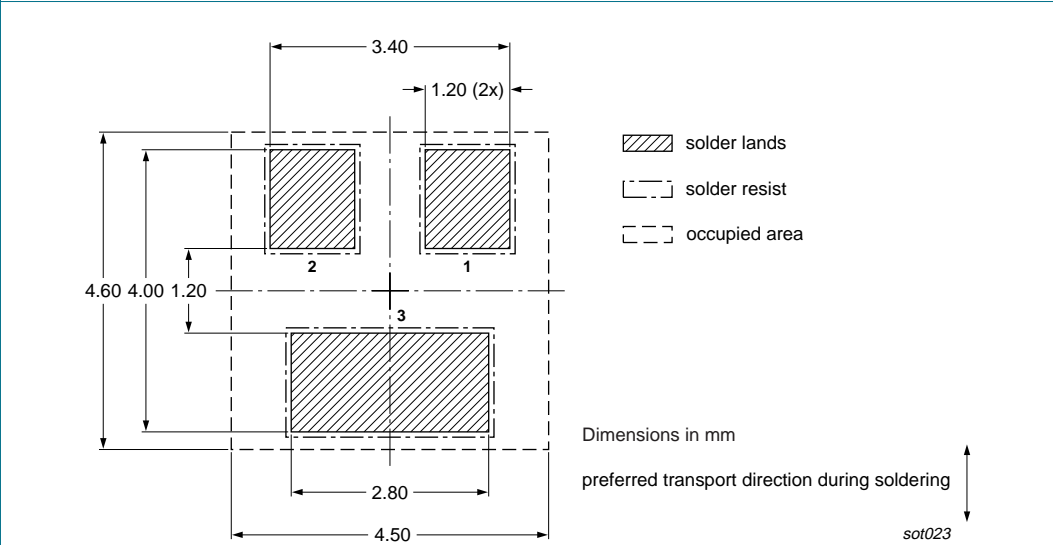


Fig 13. Wave soldering footprint SOT23 (TO-236AB)

11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PBRP113ZT_1	20080116	Product data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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